



Description

JMT P-channel Enhancement Mode Power MosFET

Features

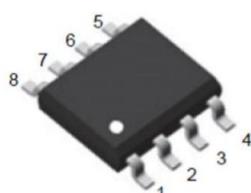
- -30V, -7A
- $R_{DS(ON)} < 25.6\text{m}\Omega$ @ $V_{GS} = -10\text{V}$
- $R_{DS(ON)} < 35.8\text{m}\Omega$ @ $V_{GS} = -4.5\text{V}$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free

Applications

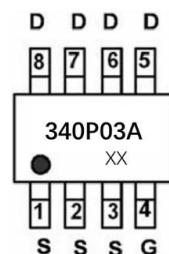
- Load Switch
- PWM Application
- Power Management



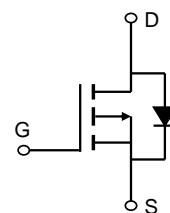
100% UIS TESTED!
100% ΔV_{ds} TESTED!



SOP-8



Marking and Pin Assignment



Schematic

Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
340P03A	JMTP340P03A	TAPING	SOP-8	13"	4000	48000

Absolute Maximum Ratings (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	-30	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current $T_A = 25^\circ\text{C}$	-7	A
		-4.4	
I_{DM}	Pulsed Drain Current ⁽¹⁾	-28	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	20	mJ
P_D	Power Dissipation $T_A = 25^\circ\text{C}$	1.6	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	79	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1.0	-1.7	-2.5	V
$R_{\text{DS(ON)}}$	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = -10\text{V}, I_D = -7\text{A}$	-	19.7	25.6	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -4\text{A}$	-	27.5	35.8	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = -15\text{V}, f = 1\text{MHz}$	-	860	-	pF
C_{oss}	Output Capacitance		-	109	-	pF
C_{rss}	Reverse Transfer Capacitance		-	84	-	pF
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ to } -10\text{V}$ $V_{DS} = -15\text{V}, I_D = -5\text{A}$	-	16	-	nC
Q_{gs}	Gate Source Charge		-	3	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	3	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{GS} = -10\text{V}, V_{DD} = -15\text{V}$ $I_D = -5\text{A}, R_{\text{GEN}} = 3\Omega$	-	4	-	ns
t_r	Turn-On Rise Time		-	2	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	38	-	ns
t_f	Turn-Off Fall Time		-	22	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	-7	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-28	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = -5\text{A}$	-	-	-1.2	V
trr	Body Diode Reverse Recovery Time	$I_F = -5\text{A}, di/dt = 100\text{A/us}$	-	10	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	3	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = -15\text{V}$, $V_G = -10\text{V}$, $R_G = 25\text{ohm}$, $L = 0.5\text{mH}$, $I_{AS} = -9\text{A}$

3. $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB

4. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Typical Performance Characteristics

Figure 1: Output Characteristics

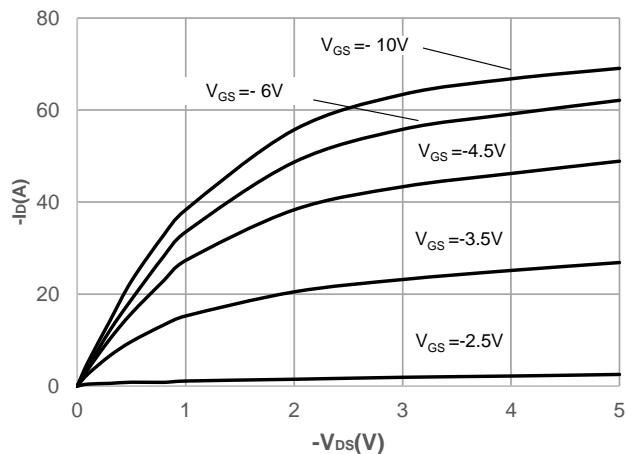


Figure 2: Typical Transfer Characteristics

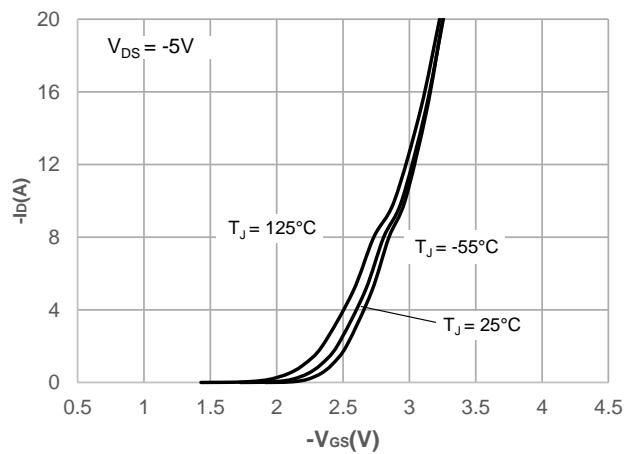


Figure 3: On-resistance vs. Drain Current

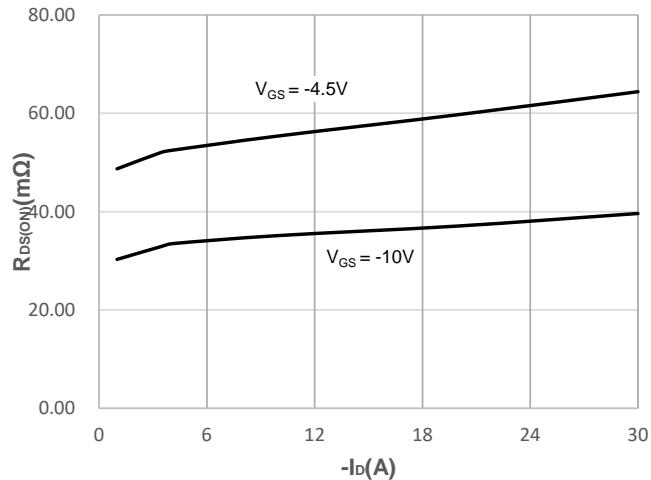


Figure 4: Body Diode Characteristics

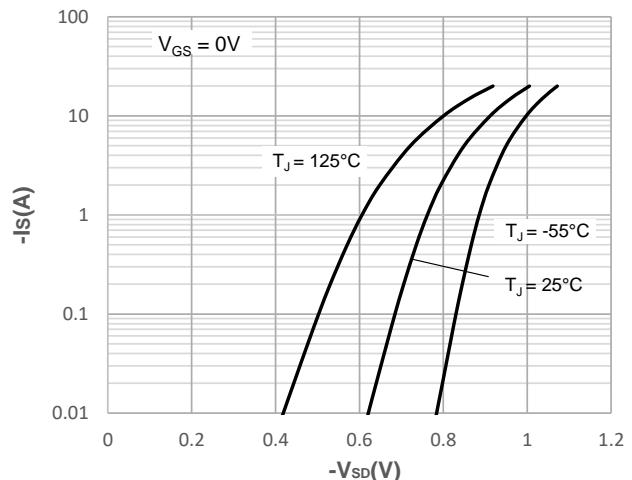


Figure 5: Gate Charge Characteristics

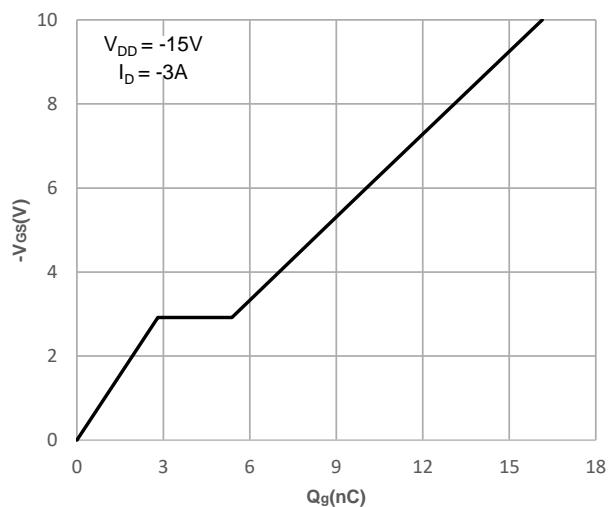
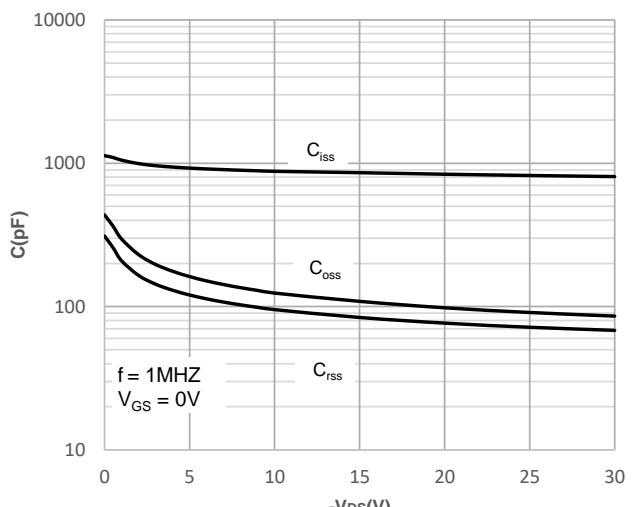


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

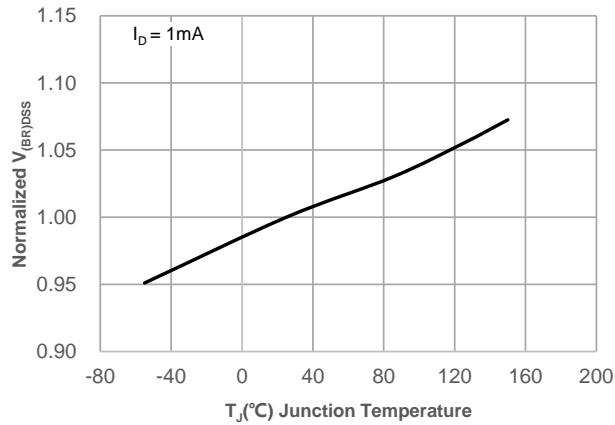


Figure 8: Normalized on Resistance vs. Junction Temperature

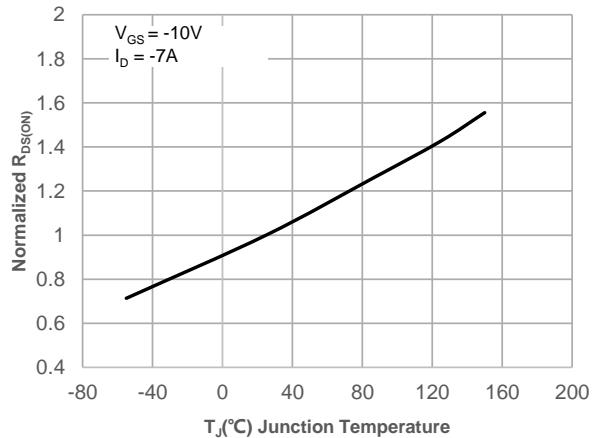


Figure 9: Maximum Safe Operating Area

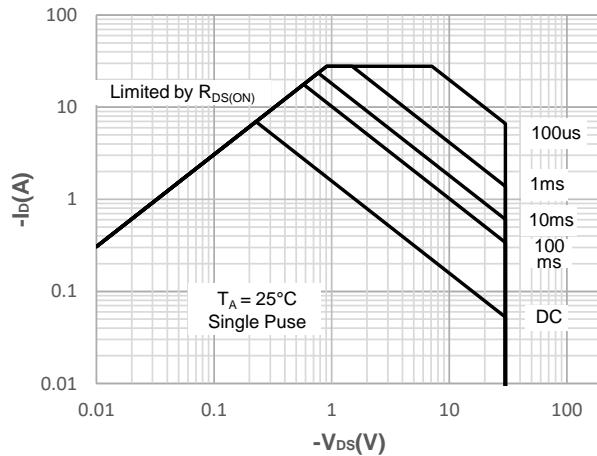


Figure 10: Maximum Continuous Drian Current vs. Ambient Temperature

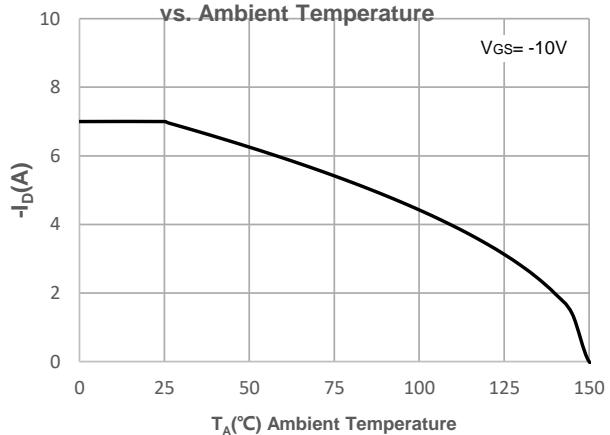


Figure 11: Normalized Maximum Transient Thermal Impedance

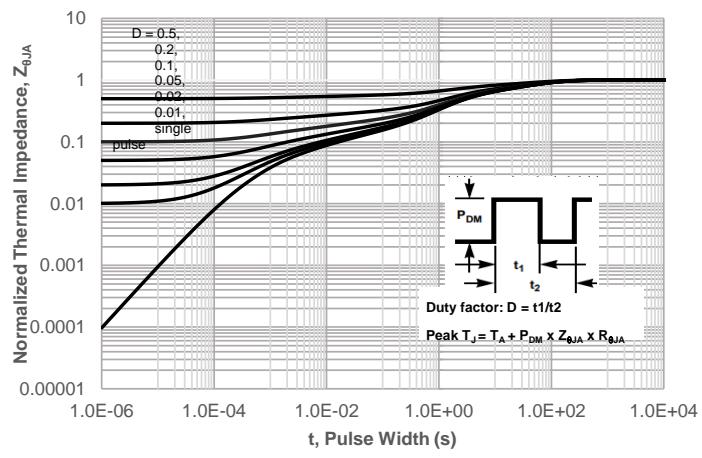
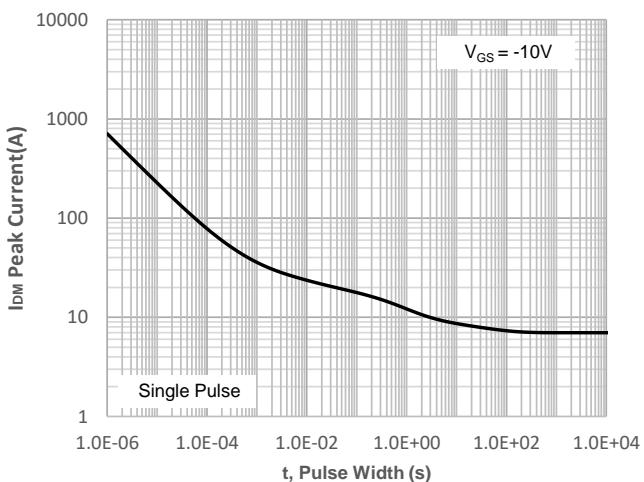


Figure 12: Peak Current Capacity



Test Circuit

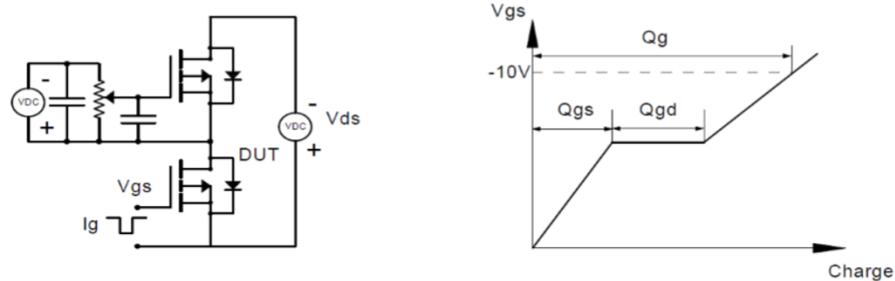


Figure 1: Gate Charge Test Circuit & Waveform

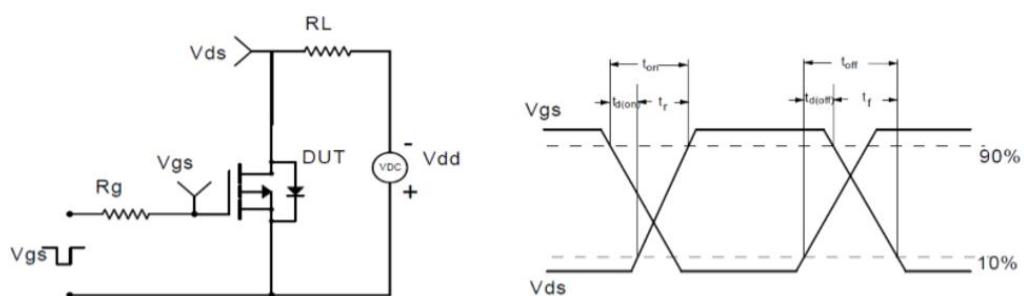


Figure 2: Resistive Switching Test Circuit & Waveform

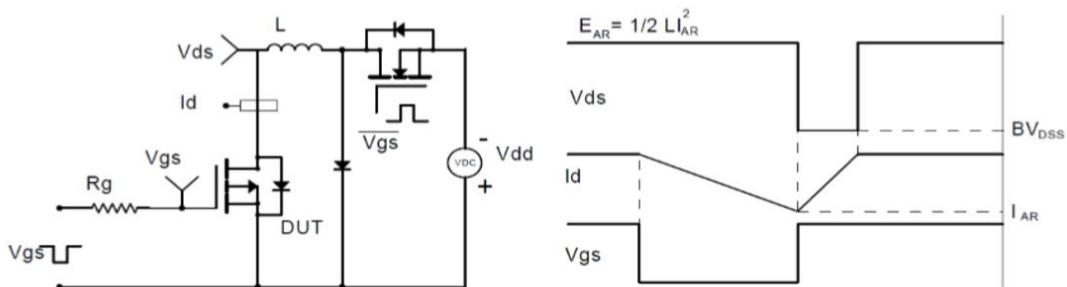


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

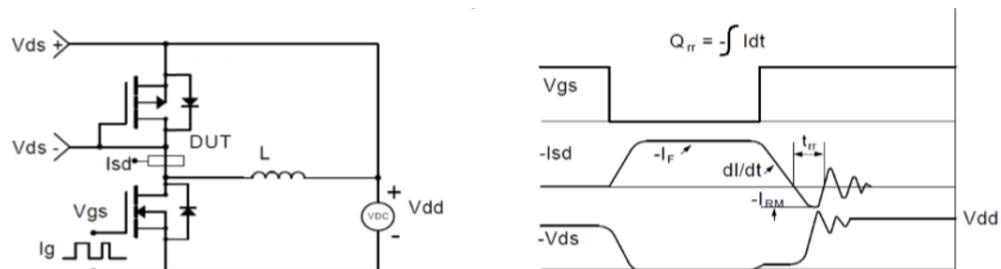
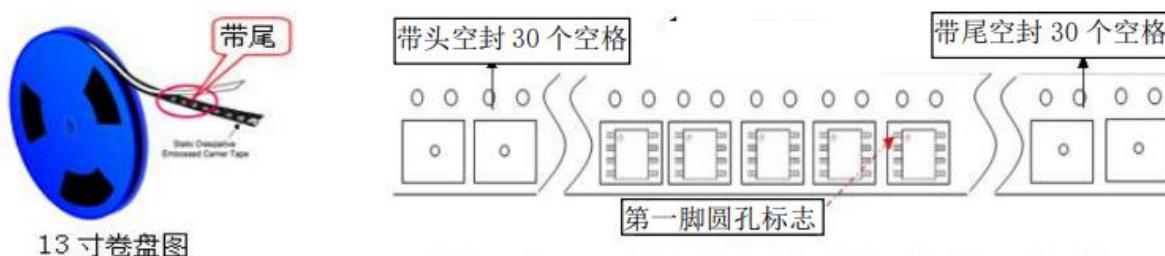
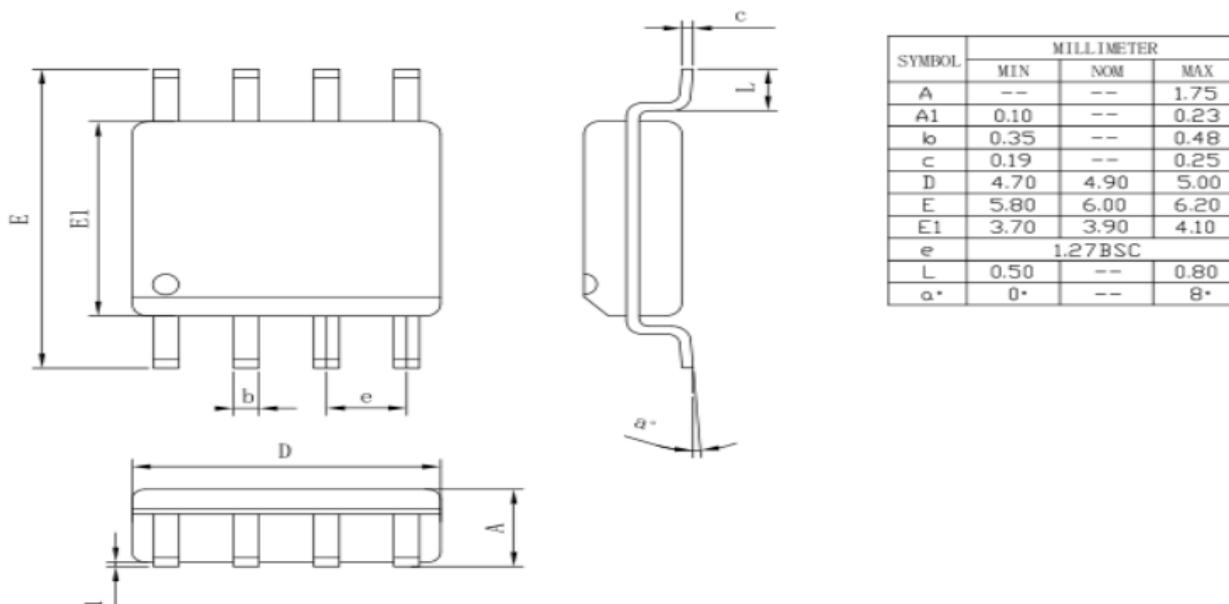


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(SOP-8)



S07/8、ESOP-8 产品带头 (30 个空格)、带尾 (30 个空格)

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